

Product Name	S-3049
Product Category	Conductive Adhesive
Use	Semiconductor Modules, Car Electro Devices, General Modules, Die Attach, Touch Panel, Solar Battery
Function	One Component Type, High Adhesive Strength, Good Adhesive at High Temperature

Item	Condition	Unit	Typical Value
General Item			
Package	–	–	Pot, Syringe
Liquid Feature			
Viscosity	B type viscometer / 10rpm / @25°C	Pa·s	75
Storage Stability	Unopen / Frozen (below -15°C)	–	3 months
Cured Properties			
Recommended Curing Condition	Heat air circulation oven	–	170°C x 60 minutes
Volume Resistivity	170°C x 60 minutes cure	Ω·cm	4.5 x 10 ⁻⁴
Shear Adhesive Strength @25°C	4mm ² Si chip/Au plated surface	N/mm ²	24.8
	4mm ² Si chip/Alumina substrate		22.3
Shear Adhesive Strength @150°C	4mm ² Si chip/Au plated surface		18.6
Characteristics	Conductive adhesive of good adhesion Good adhesive strength at high temperature		

The above values are reference and not specification.



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